

### **REMARKS**

Claims 1-11 and 46-52 were pending in this application when the present Office Action was mailed (April 11, 2007). Claims 8 and 10 have been withdrawn from consideration in response to a prior Restriction Requirement. In this response, claims 1 and 46 have been amended without prejudice to pursuing these claims in unamended or other forms in a continuation or other application. Claims 50-52 were canceled without prejudice to pursuing these claims in a continuation or other application. Claims 53-55 have been added. Accordingly, claims 1-11, 46-49, and 53-55 are currently pending.

In the April 11, 2007 Office Action, all of the pending claims were rejected. More specifically, the status of the application in light of this Office Action is as follows:

(A) Claims 1-7, 9, and 11 were rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,784,525 to Kuan et al. ("Kuan"); and

(B) Claims 1-7, 9, 11, and 46-52 were rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent Application Publication No.2002/0046854 to Huang et al. ("Huang").

As a preliminary matter, the undersigned attorney wishes to thank the Examiner for engaging in a telephone interview on June 26, 2007. During the telephone interview, the claimed subject matter and the teachings in Kuan and Huang were discussed. The following remarks reflect and expand upon the points discussed during the June 26 telephone interview. The applicants accordingly request that this paper also constitute the applicants' Interview Summary. If the Examiner notices any deficiencies in this regard, the Examiner is encouraged to contact the undersigned representative.

A. Response to the Section 102(e) Rejection under Kuan

Claims 1-7, 9, and 11 were rejected under 35 U.S.C. § 102(e) as being anticipated by Kuan. The applicants respectfully traverse this rejection. For the reasons discussed below, Kuan does not support a Section 102 rejection of these claims. The applicants also note that the characterization of Kuan below is directed toward the description of Kuan's disclosure and should not be construed in any way to limit or interpret terms of Kuan's claims.

As discussed during the June 26 telephone interview, Kuan discloses a first lead 26 having terminal contacts 16 and a second lead 28 electrically connected to the first lead 26 with a connector 38. Even assuming, for the sake of argument, that the end surface (e.g., on the left of Figure 2, near the reference numeral 24) of the second lead 28 corresponds at least in part to the first package contacts of claim 1, the end surface of the second lead is not accessible for electrical coupling in a direction that is "opposite" to a direction for accessing the terminal contacts 16. Instead, the end surface of the second lead appears to be accessible in a direction that is 90° from the direction for accessing the terminal contacts 16. As a result, the Section 102 rejection of claim 1 should be withdrawn. Claims 2-7, 9, and 11 depend from claim 1. As a result, the Section 102 rejection of these claims should be withdrawn for the reasons discussed above, and for the additional features of these claims.

B. Response to the Section 102(e) Rejection under Huang

Claims 1-7, 9, 11, and 46-52 were rejected under 35 U.S.C. § 102(e) as being anticipated by Huang. Claims 50-52 have been canceled without prejudice to pursuing these claims in a continuation, continuation-in-part, or other application, and accordingly, the rejection of these claims are moot. The applicants respectfully disagree with the merits of the rejection of independent claims 1 and 46; however, in an effort to expedite prosecution, these claims have been amended to further clarify the claimed subject matter. Support for the amended subject matter can be found at, e.g., Figures 1A-C. For the reasons discussed below, Huang does not support a Section 102 rejection of these claims.

Claim 1 is directed to a microfeature device package system that includes a microfeature device, a plurality of device contacts electrically coupled to structures within the microfeature device, and a conductive structure at least partially enclosing a cavity housing the microfeature device and electrically connected to at least one of the plurality of device contacts. The conductive structure has a plurality of first and second package contacts accessible for electrical coupling to at least one device external to the package. The first package contacts are accessible from a first direction for coupling, and the second package contacts are configured to receive solder balls and are accessible from a second direction for coupling. The second direction is opposite the first direction. The system also includes an encapsulant disposed adjacent to the

microfeature device and the conductive structure. The encapsulant has apertures with aperture walls aligned with the second package contacts and containing solder balls carried by the second package contacts. The encapsulant is positioned against the conductive structure proximate to the first package contacts. The system further includes individual volumes of solder positioned at individual first package contacts.

Huang discloses, *inter alia*, a semiconductor package that includes a non-conductive base layer 51, a plurality of leads 52 adhered to the base layer 51, a chip 53 attached to the leads 52, and an encapsulant 55 for encapsulating the chip 53 and the leads 52. (page 3, paragraph [0040]) The encapsulant can be formed to expose the lower surface of an outer end portion of the leads 52 for allowing stacking of the packages. (page 3, paragraph [0048])

Huang does not support a Section 102 rejection of claim 1 because Huang fails to disclose several features of this claim. For example, Huang does not disclose "a conductive structure having a cavity housing the microfeature device and electrically connected to at least one of the plurality of device contacts." Instead, Huang's leads 52 appear to be straight leads that cannot form "a conductive structure having a cavity" housing the chip 53. As a result, the Section 102 rejection of claim 1 based on Huang should be withdrawn. Claims 2-7, 9, and 11 depend from claim 1. As a result, the Section 102 rejection of these claims should be withdrawn for the reasons discussed above, and for the additional features of these claims.

Claim 46 has been amended to include subject matter generally similar to that of claim 1. As a result, the Section 102 rejection of claim 46 should be withdrawn for the reasons discussed above, and for the additional features of this claim. Claims 47-49 depend from claim 46. As a result, the Section 102 rejection of these claims should be withdrawn for the reasons discussed above, and for the additional features of these claims.

#### C. Newly Added Claims

Claims 53-55 have been added in this response. The applicants respectfully submit that these claims are also patentable over the cited references for including features not disclosed by these references. For example, claim 53 includes "a leadframe at least partially enclosing a

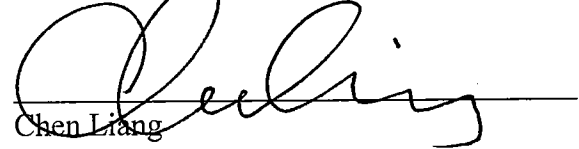
cavity housing the microfeature device and electrically connected to at least one of the plurality of device contacts," which is not disclosed in the cited references.

D. Conclusion

In view of the foregoing, the pending claims comply with the requirements of 35 U.S.C. § 112 and are patentable over the applied art. The applicants accordingly request reconsideration of the application and a Notice of Allowance. If the Examiner has any questions or believes a telephone conference would expedite prosecution of this application, the Examiner is encouraged to contact Chen Liang at (206) 359-6038.

Respectfully submitted,

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Date: 7/11/07

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